

In the Claims:

Please amend the claims as follows:

Please replace pending claim 1 with the following claim having the same number, and replacement claim 1 is also shown in re-written form, with underlining showing additions, on a sheet attached to this Amendment and filed herewith:

- 1 (twice amended). An integrated package comprising:  
a substrate having a plurality of peripheral openings and first and second surfaces;  
a chip adhered to said second surface of said substrate;  
a plurality of electrical conductors physically attached to said chip and located such that  
5 each electrical conductor in said plurality of electrical conductors is aligned within a respective one of said plurality of peripheral openings in said substrate;  
a plurality of pads disposed on said first surface of said substrate generally centralized within said peripheral openings of said substrate; and  
potting material filling said peripheral openings.

Please replace pending claim 6 with the following claim having the same number, and replacement claim 6 is also shown in re-written form, with underlining showing additions, on a sheet attached to this Amendment and filed herewith:

- 6 (amended). The integrated circuit package as recited in claim 1 further comprising a plurality of solder balls disposed on said pads.

Please add the following new claim 21:

-- 21. The integrated circuit package of claim 1 wherein each of the plurality of conductors comprises a bonding pad. --

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[Please add the following new claim 22:]

-- 22. An integrated package comprising:

a substrate having a plurality of peripheral opening and first and second surfaces;

a chip comprising an operative side and a non-operative side, wherein said chip is adhered to said second surface of said substrate such that the non-operative side faces away from the substrate;

5 a plurality of pads disposed on said first surface of said substrate generally centralized within said peripheral openings of said substrate; and

potting material filling said peripheral openings. --

#### REMARKS

Claims 1 through 20 were already pending in this case. The present Amendment amends the Specification, and also amends independent claims 1, 8, and 16, and makes a typographical correction to dependent claim 15. New dependent claim 21 and new independent claim 22 are added. Reconsideration and favorable action in the above-referenced application, based on the present amendments thereto and the following remarks, are respectfully requested.

#### Amendments to the Specification

The present Amendment makes a typographical change to page 23, line 7.

#### Amendment to the Drawings

Applicant submits herewith a Request For Approval To Amend Drawings consistent with the request of the Examiner.

Please replace pending claim 16 with the following claim having the same number, and replacement claim 16 is also shown in re-written form, with underlining showing additions, on a sheet attached to this Amendment and filed herewith:

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~~16~~ (twice amended). An integrated circuit package comprising:

a substrate having a plurality of peripheral openings, first and second surfaces and an outline;

a plurality of routing strips being integral with said substrate;

5 a plurality of pads centrally disposed on said first surface at least one of said pads being electrically connected with said routing strips;

a chip adhered to said second surface of said substrate, said chip having an outline that is substantially the same as said outline of said substrate and having a plurality of bonding pads physically attached to the chip and located such that each bonding pad in said plurality of 10 bonding pads is aligned within a respective one of said plurality of peripheral openings in said substrate;

wire bonding electrically connecting said bonding pads to said routing strips;

vias connecting said routing strips to said pads;

potting material filling said peripheral openings and covering said wire bonding and 15 said bonding pads; and

a plurality of solder balls centrally disposed on said pads disposed on said first surface of said substrate.